

Seikoh Giken SFP-550 Polishing Instructions for Pre-Domed or Pre-Angled Zirconia Ferrule Connectors

Fiber Optic CenterTM, Inc., the global supplier of AngströmLap[®], the most widely used lapping film in the world, is also an industry leader in cost effective high performance ultra PC and angled single mode polishing processes for volume assembly production.

Achieving consistent results that meet the demanding technical specifications for single mode systems requires the optimization of many factors throughout the termination and testing process. These include:

- suitable single mode fiber
- suitable epoxy
- proper mixing, application & curing of epoxy
- connector quality & tolerances
- pressure & time of polishing at each step
- lapping film quality & consistency
- lapping film grit sizes & materials

- polishing solutions
- adapter quality & tolerances
- calibration & quality of test instruments & reference cables
- test methods & conditions
- overall cleanliness
- specific cleaning procedures

Instructions

When used with the SFP-550 and the materials listed below, the UPC and APC polishing processes requires between 5-10 minutes for up to 20 or 32 2.5 mm connectors or up to 24 or 40 1.25 mm connectors:

- Prior to loading connectors into the polishing fixture, perform a quick de-nubbing or air polish to remove the sharp edges from the fiber and to get the fiber flush with the epoxy. Ten to 15 small circles should be enough, but will vary according to cleave length.
- Use 70 or 80 durometer rubber pads for 2.5mm ferruled connectors, p/n PR5X-500-70 or 80, and 90 durometer rubber pads for the 1.25mm ferruled connectors, PR5X-480-90. Use a separate rubber pad for each step. Using the correct rubber pad will help create the correct Radius of Curvature.
- Clean rubber pads with at least 99% pure isopropyl alcohol and lint free wipes. ITW Chemtronics 6704 Econowipes or CleanTex 604 lint free wipes are recommended to insure no contamination occurs during the cleaning process.

- 4. Use a minimal amount of distilled water to adhere lapping films to rubber pads. Make sure air bubbles are kept to minimum, and no debris is trapped between the film and rubber pad. A piece of double sided tape can be used to help keep lapping film on the pads.
- 5. Between each polishing step flush out connector end-faces, work-holder surface, lapping film surface, bottom of rubber pad, surface rubber pad rests on with de-ionized water. Then wipe with lint-free wipe, and blast with compressed or canned air, p/n ES1217. Proper cleaning will help insure a scratch, pit or defect free end-face.
- Refer to tables below for recommended process. Please note processes are for preangled and pre-domed connectors.

Technical Specifications

SM UPC Back-Reflection¹ = -55dB or less

MM UPC Back-Reflection¹ = -35dB or less

SM APC Back-Reflection¹ = -70dB or less

SM/MM Insertion Loss¹ = 0.2db or less

Fiber Height = Telcordia GR-326v3 Apex Offset = 50um or less

Radius of Curvature = 7-25mm

¹Typical results for high quality connector. Optical results are dependent on connector quality.

Polishing Timetables

2.5mm Polishing Process - Table 1.1

Polishing Step	Material & Grit Size	Pressure/Pad ¹	Time	Fluid	Usage ²	Part Number
Epoxy Removal ³	Gray Silicon Carbide 9 um	PR5X-500-70	15-30 sec.	de-ionized water	1-5	SC9T503N100
Rough Polish	Orange Diamond 5 um	PR5X-500-70	60 sec.	de-ionized water	10-30	D5BF503N1
Medium Polish	Lavender Diamond 1 um	PR5X-500-70	60 sec.	de-ionized water	20-30	D1KT503N1
Final Polish⁴	White SiO ₂ , Sub-Micron	PR5X-500-70	60-90 sec.	de-ionized water	3	SEQFPF503N100
Cleaning⁵	Brown Flocked Pile, None	PR5X-500-70	15-20 sec.	de-ionized water	10	ABR60NC502N1

1.25mm Polishing Process - Table 1.2

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Polishing Step	Material & Grit Size	Pressure/Pad ¹	Time	Fluid	Usage ²	Part Number
Epoxy Removal ³	Gray Silicon Carbide 9 um	PR5X-480-90	15-30 sec.	de-ionized water	1-5	SC9T503N100
Medium Polish	Lavender Diamond 1 um	PR5X-480-90	60 sec.	de-ionized water	20-30	D1KT503N1
Final Polish⁴	White SiO₂, Sub-Micron	PR5X-480-90	60-90 sec.	de-ionized water	3	SEQFPF503N100
Cleaning ⁵	Brown Flocked Pile, None	PR5X-480-90	15-20 sec.	de-ionized water	10	ABR60NC502N1

Final Polish Film Options

As a leader in single mode polishing, Fiber Optic Center, ™ Inc. always looks for process improvements. Most innovations occur at the final step. Some other final polish options that achieve superior results are as follows:

Final Polish Options - Table 2

Polishing Step	Material & Grit Size	Pressure/Pad ¹	Time	Fluid	Usage ²	Part Number
	Translucent	PR5X-500-70 (for 2.5 mm)		de-ionized		
Final Polish	SiO ₂ , Sub-Micron	PR5X-480-90 (for 1.25 mm)	60-90 sec.	water	1	FOS-01
	Translucent	PR5X-500-70 (for 2.5 mm)		de-ionized		
Final Polish	SiO ₂ , Sub-Micron	PR5X-480-90 (for 1.25 mm)	60-90 sec.	water	1	863XW-503N
	Yellow	PR5X-500-70 (for 2.5 mm)		de-ionized		
Final Polish	SiO ₂ , Sub-Micron	PR5X-480-90 (for 1.25 mm)	90-120 sec.	water	5	ALG15XY503N100
	Light Blue	PR5X-500-70 (for 2.5 mm)		Ultra Polish		
Final Polish	AlOx, 0.3 um	PR5X-480-90 (for 1.25 mm)	15-30 sec.	Solution	1	CA03F502N100

¹ Pressure is controlled by the thickness of the rubber pad and does not have to be adjusted when polishing differing numbers of connectors.

Ordering Information

For more information on this or other products and their availability, please contact Fiber Optic Center, ™ Inc. at (800) 473-4237 or (508) 992-6464, fax at (508) 991-8876, or e-mail at sales@focenter.com.

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² Usage estimates are conservative, and may vary. Flushing out lapping film with generous amounts of distilled water will increase the life of the

³ Pressure and time will vary. Object is to only remove the epoxy and to stop as soon as epoxy is removed from all connectors.

⁴ Please note other final polish film options below. For **Optimum MM polishing** the SEQFPF should still be used, but for a more **Economical** MM process, this step can either be eliminated, or substituted with the AlOx 0.3um film listed below.

⁵ Optional, but recommended, cleaning step.